

VXE4 6.0 x 3.5mm Crystal

Standard Crystal Datasheet

Helping Customers Innovate, Improve & Grow

Table 2. Pinout

Function

Crystal

Connected to cover

(Connect to GND

Crystal

Connected to cover

(Connect to GND)

Pin

1

2

3

4

Table 1. Electrical Performance							
Parameter	Symbol	Min.	Тур	Max	Units		
Nominal Frequency	F _{NOM}	8.000		100.000	MHz		
Mode		Fundan					
Operating Temperature Range	T _{OP}	0/70, -10/70, -20/70, -40/85 °C					
Stability Over T _{op} ¹	F _{stab}	±10		±100	ppm		
Frequency Tolerance ²	F _{TOL}		±10	±20	ppm		
Load Capacitance	CL	6		32	pF		
Shunt Capacitance	C _°			5	pF		
Drive Level			10	100	uW		
Aging / 1st year (at 25 °C)	F _{AGE}			±5	ppm		
Insulation Resistance		500			MOhm		
Storage Temperature	Τ _{sto}	-40		90	°C		
		eries Resistance					
Crystal Frequency 8.000MHz-10.000MHz 10.001MHz-14.000MHz 14.001MHz-20.000MHz 20.001MHz-50.000MHz 35.000MHz-48.000MHz 48.001MHz-100.000MHz	ESR			60 50 40 30 100 80	Ohm		

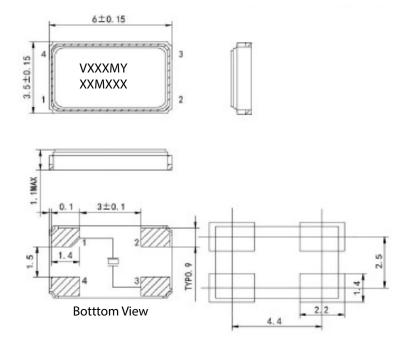
Notes:

1. Referenced to the Frequency at 25 °C.

2. Frequency measured at 25 °C \pm 3 °C.

Product is compliant to RoHS directive and fully compatible with lead free assembly.

Package Drawing



Part Marking:

V = Vectron XXX = Ordering Option M = Month A = January B = February

- $\mathsf{D} = \mathsf{April}$
- $\mathsf{E} = \mathsf{May}$
- F = June
- G = July H = August
- I = September
- J = October
- K = November
- L = December
- Y = Year
- XXMXXX = Frequency

All Dimensions in mm

Table 3. Environmental Compliance						
Parameter	Conditions					
Mechanical Shock	MIL-STD-883, Method 2002, Condition B					
Mechanical Vibration	MIL-STD-883, Method 2007, Condition A					
Temperature Cycle	MIL-STD-883, Method 1010, Condition B					
Solderability	MIL-STD-202-210, Condition B					
Gross and Fine Leak	MIL-STD-883, Method 1014					
Altitude	MIL-STD-883, Method 1001, Condition B					
Moisture Sensitivity Level	MSL 1					
Contact Pads	Gold (0.3 um min) over Nickel					
Weight	63 mg					

Reliability & IR Compliance

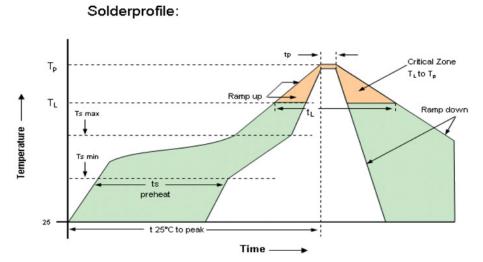
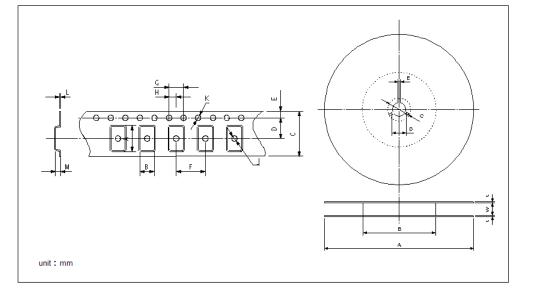


Table 4. Reflow Profile								
Parameter	Symbol	Value						
PreHeat Time Ts-min Ts-max	t _s	60 sec Min, 260 sec Max 150°C 200°C						
Ramp Up	R _{UP}	3 °C/sec Max						
Time Above 217 °C	t	60 sec Min, 150 sec Max						
Time To Peak Temperature	T _{AMB-P}	480 sec Max						
Time at 260 °C	t _P	30 sec Max						
Ramp Down	R _{DN}	6 °C/sec Max						

Pads are Au over Ni and compatible with either SnPb or Pb free attachment. MSL: 1

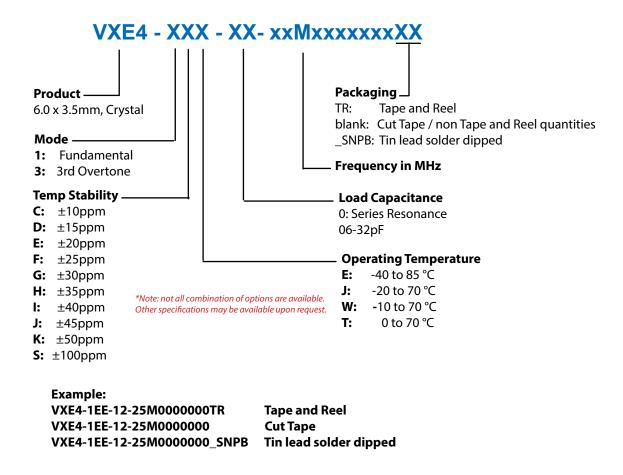
Tape & Reel

Table	Table 5. Tape and Reel Dimensions (mm)																	
Таре												Reel						
Α	В	С	D	E	F	G	н	J	К	L	М	А	В	С	D	Е	W	Т
6.4	3.9	12.0	5.5	1.75	8.0	4.0	2.0	1.5	1.55	0.3	1.4	180	180	21.0	13.0	2.0	12.4	2.0



1K pieces per reel

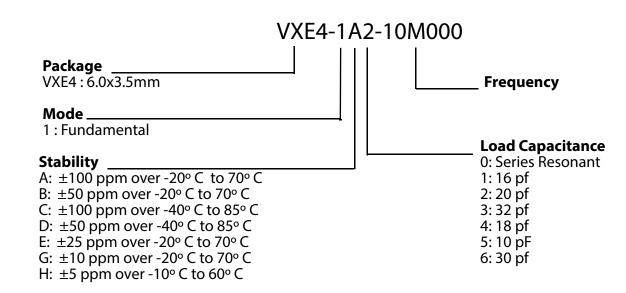
Ordering Information



Revision History

Revision Date	Approved	Description
August 29, 2016	RC	Initial datasheet for factory approval and release to customer.
August 10, 2018	FB	Update logo and contact information, add "SNPBDIP" ordering option
June 07, 2019	FB	Update logo and contact information, add Table 2 Environmental compliance, change "SNPBDIP" to "SNPB"
April 30, 2020	FB	Add tape and rell ordering option

Previous Ordering Information for Reference Only Do Not Use to Build a New Part Number



The ordering codes for the VXE4 were changed in 2016. If you had ordered a specific code based off this ordering method, it is still available for purchase under the old code however no new part numbers will be created using this system.

Due to the change in the 8th character from numeric to alphabetic, there is no opportunity for overlap between the two ordering methods.

Contact Information

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